



Indra Ganesan

COLLEGE OF ENGINEERING

Approved by AICTE, New Delhi & Affiliated to Anna University, Chennai
Accredited by NAAC with 'B+' Grade, 2(f) & 12B Status Institution by UGC

IG Valley, Madurai Main Road, Manikandam, Tiruchirappalli - 620012

NAAC DOCUMENTS

QUALITY INDICATOR FRAME WORK

CRITERION – 1

CURRICULAR ASPECTS

SUBMITTED BY

IQAC

INTERNAL QUALITY ASSURANCE CELL

INDRA GANESAN COLLEGE OF ENGINEERING





Indra Ganesan

COLLEGE OF ENGINEERING

Madurai Main Road (NH-45B), Manikandam, Tiruchirappalli - 620 012
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NAAC Accredited, 2(F) Status Institution by UGC



Criteria 1	Curricular Aspects	100
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1.1 Curricular Planning and Implementation (20)

1.1.1 The Institution ensures effective curriculum planning and delivery through a well-planned and documented process including Academic calendar and conduct of continuous internal Assessment

Table of Content

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INDRA GANESAN COLLEGE OF ENGINEERING

IG Valley, Manikandam, Tiruchirappalli, Tamil Nadu – 620 012, India
(Approved by AICTE, New Delhi, Affiliated to Anna University, Chennai-25)

DEPARTMENT OF ELECTRONICS AND COMMUNICATION

ENGINEERING

PREFACE OF THE COURSE FILE

Batch : 2016-2020

Academic Year : 2018-2019 / EVEN

Program : ELECTRONICS AND COMMUNICATION ENGINEERING

Year & Semester : 3rd Year / 6th Semester / 'B' Section

Course Code : EC 6601 NBA Course Code: C312

Name of the Course : VLSI DESIGN

Faculty in-charge : Ms.M.NANDHINI/ AP / ECE

M. Namu
Signature of the Faculty in-charge

N. G. Jeythi
HoD / EC

Dr. G. Balakrishnan, M.E., Ph.D.,
Principal
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DEPARTMENT OF ELECTRONICS AND COMMUNICATION

ENGINEERING

Syllabus

EC6601 VLSI DESIGN

L T P C 3 0 0 3

OBJECTIVES:

- In this course, the MOS circuit realization of the various building blocks that is common to any
- microprocessor or digital VLSI circuit is studied. Architectural choices and performance tradeoffs involved in designing and realizing the circuits
 - in CMOS technology are discussed. The main focus in this course is on the transistor circuit level design and realization for digital
 - operation and the issues involved as well as the topics covered are quite distinct from those encountered in courses on CMOS Analog IC design.

UNIT I MOS TRANSISTOR PRINCIPLE

9

NMOS and PMOS transistors, Process parameters for MOS and CMOS, Electrical properties of CMOS circuits and device modeling, Scaling principles and fundamental limits, CMOS inverter scaling, propagation delays, Stick diagram, Layout diagrams

UNIT II COMBINATIONAL LOGIC CIRCUITS

9

Examples of Combinational Logic Design, Elmore's constant, Pass transistor Logic, Transmission gates, static and dynamic CMOS design, Power dissipation – Low power design principles

UNIT III SEQUENTIAL LOGIC CIRCUITS

9

Static and Dynamic Latches and Registers, Timing issues, pipelines, clock strategies, Memory architecture and memory control circuits, Low power memory circuits, Synchronous and Asynchronous design

UNIT IV DESIGNING ARITHMETIC BUILDING BLOCKS

9

Data path circuits, Architectures for ripple carry adders, carry look ahead adders, High speed adders, accumulators, Multipliers, dividers, Barrel shifters, speed and area tradeoff

UNIT V IMPLEMENTATION STRATEGIES

9

Full custom and Semi custom design, Standard cell design and cell libraries, FPGA building block architectures, FPGA interconnect routing procedures.

TOTAL: 45 PERIODS

OUTCOMES:

- Upon completion of the course, students should
- Explain the basic CMOS circuits and the CMOS process technology.
 - Discuss the techniques of chip design using programmable devices.

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- Model the digital system using Hardware Description Language.

TEXTBOOKS:

1. Jan Rabaey, Anantha Chandrakasan, B.Nikolic, "Digital Integrated Circuits: A Design Perspective", Second Edition, Prentice Hall of India, 2003.
2. M.J. Smith, "Application Specific Integrated Circuits", Addison Wesley, 1997

REFERENCES:

1. N.Weste, K.Eshraghian, "Principles of CMOS VLSI Design", Second Edition, Addison Wesley 1993
2. R.Jacob Baker, Harry W.LI., David E.Boyce, "CMOS Circuit Design, Layout and Simulation", Prentice Hall of India 2005
3. A.Pucknell, Kamran Eshraghian, "BASIC VLSI Design", Third Edition, Prentice Hall of India, 2007.



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DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Faculty Time Table

Ms.M.Nandhini								
Day Order	1	2	3	4	5	6	7	8
I		EC6601						
II	EC6601							
III								
IV			EC6601					
V		EC6601						
S.Code	Title			Year / Branch		Hours		
EC6601	VLSI DESIGN			III / ECE B		4		
TOTAL - 4 hours								


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DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Lecture Schedule

Degree/Program: B.E / ECE
Duration: Dec 2018 - Apr 2019

Course code & Name: EC6601 –VLSI Design
Semester: VI Section: B Faculty : Ms.M.Nandhini

AIM:

To expose the students to principle of operation and performance of VLSI circuits and design

OBJECTIVES:

- Understand the fundamentals of IC technology components and their characteristics
- Understand combinational logic circuits and design principles.
- Understand sequential logic circuits and clocking strategies
- Understand Memory Architecture and building blocks
- Understand ASIC Design functioning and design

PREREQUISITES: Electronic Devices, Digital Electronics

COURSE OUTCOMES:


After the course, the student should be able to:

CO	Course Outcomes	POs	PSOs
C302.1	In depth knowledge of MOS technology	1,2,3,4,11,12	1,2,3
C302.2	Explain the Combinational Logic Circuits and Design Principles	1,2,3,4,11,12	1,2,3
C302.3	Explain Sequential Logic Circuits and Clocking Strategies	1,2,3,4,11,12	1,2,3
C302.4	Explain the Memory architecture and building blocks	1,2,3,4,11,12	1,2,3
C302.5	Apply the ASIC Design Process and Testing	1,2,3,4,11,12	1,2,3
C302.6	Design using Programmable Devices (ROM, PLA, FPGA),	1,2,3,4,11,12	1,2,3

S.No	Date	Period	Topics to be Covered	Book & Page. No.
UNIT -I - Introduction to MOS Transistor Principle				Target periods :09
1	17.12.18	2	Process parameters for MOS and CMOS	1(12-16)
2	18.12.18	1	Electrical properties of CMOS circuits	1(17-20)
3	20.12.18	3	Device Modeling	1(30-34)
4	21.12.18	2	Scaling principles and fundamental limits	
5	22.12.18	1	CMOS inverter, scaling	1(25-27)
6	24.12.18	2	Propagation Delays	1(31-32)
7	27.12.18	3	Stick diagram	1(33-35)
8	28.12.18	2	Stick diagram-Contd	1(35-36)

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9	29.12.18	1	Layout diagrams	1(38-39)
UNIT II - Introduction to Combinational Logic Circuits			Target periods :09	
10	04.01.19	2	Examples of Combinational Logic Design	1(54-62) 2(2-4)
11	05.01.19	1	Elmore"s constant	1(62-71) 2(20-28)
12	07.01.19	2	Pass transistor Logic	1(71-91)
13	08.01.19	1	Transmission gates	2(29-34,66-70)
14	10.01.19	3	Examples	1(101-106)
15	11.01.19	2	Static and Dynamic CMOS Design	1(124-125)
16	18.01.19	2	Power dissipation	1(116-120)
17	19.01.19	3	Low power design principles	1(127-131)
18	21.01.19	2	Problems on Static and Dynamic CMOS Design	1(94-97)
UNIT III - Introduction to Sequential Logic Circuits			Target Periods :09	
19	28.01.19	2	Static and Dynamic Latches and Registers	1(158-160) 2(161-164)
20	29.01.19	1	Timing Issues,	1(161-172)
21	31.01.19	3	Clock Strategies	1(173-176) 2(164-184)
22	01.02.19	2	Memory Architecture and Memory Control Circuits	1(176-178) 2(185-202)
23	02.02.19	2	Low Power Memory Circuits	1(216-223) 2(285-293)
24	04.02.19	2	Synchronous Design	2(223-229) 1(223-239)
25	05.02.19	1	Asynchronous Design	1(247-249)
26	07.02.19	3	Asynchronous Design-Contd	Material
27	08.02.19	2	Pipelines	Material
UNIT IV - Introduction to Designing Arithmetic Building Blocks			Target Periods :09	
28	18.02.19	2	Data Path Circuits	1(285-287) 2(360-365)
29	19.02.19	1	Architectures For Ripple Carry Adders	
30	21.02.19	3	Multipliers	1(287-302)
31	22.02.19	2	Manchester carry chain adder	1(305-307)
32	23.02.19	3	Carry Look Ahead Adders	1(308-309)
33	25.02.19	2	Dividers	1(305-307)
34	26.02.19	1	High Speed Adders	1(311-313)
35	28.02.19	3	Accumulators	1(326-327)
36	01.03.19	2	Speed And Area Tradeoff	1(328-329)
UNIT V - Introduction to Implementation Strategies			Target Periods:09	
37	07.03.19	3	ASIC	1(285-287)
38	08.03.19	2	Full custom and Semi custom design	1(361-367)
39	09.03.19	2	Standard Cell Design	1(381-405)
40	11.03.19	2	Cell Libraries	1(408-410)
41	12.03.19	1	FPGA	1(337-340)
42	14.03.19	3	FPGA building block architectures	1(412-415)
43	15.03.19	2	FPGA Interconnect	1(419-421)


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44	16.03.19	1	Routing Procedures	Material
45	18.03.19	2	Routing Procedures-Contd	Material
Content Beyond the Syllabus				
46			Scan based test techniques	Material
47			Application Specific Integrated Circuits	Material

Book Reference - Text Books

Sl.	Title of the Book	Author	Publisher	Year
1.	Digital Integrated Circuits: A Design Perspective	Jan Rabaey, Anantha Chandrakasan, B.Nikolic	Prentice Hall of India	2003
2.	Application Specific Integrated Circuits	M.J. Smith	Addison Wesley	1997

Book Reference – References

Sl	Title of the Book	Author	Publisher	Year
1.	Principles of CMOS VLSI Design	N.Weste, K.Eshraghian	Addison Wesley	1993
2.	CMOS Circuit Design, Layout and Simulation	R.Jacob Baker, Harry W.Li., David E.Boyee	Prentice Hall of India	2005
3.	BASIC VLSI Design	A.Pucknell, Kamran Eshraghian	Prentice Hall of India	2005

Website Reference:

<http://nptel.iitm.ac.in/courses.php?branch=Electrical>
www.freebookspot.com

M. Nandini
 Signature of the Faculty in-charge

N. Srinivasan
 HoD ECE

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DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

Identification of Curricular Gap & Content Beyond Syllabus(CBS)

Name of the Faculty :Ms.M.Nandhini

Course Code & Name:EC 6601&VLSI Design

Degree & Program:B.E. /ECE

Semester & Section: III / B

Academic Year: 2018 -2019 /EVEN

I. Mapping of Course Outcomes with POs & PSOs.(before CBS)

Table.1 Mapping of COs, C, PSOs with POs - before CBS.

Course	PO1	PO2	PO3	PO4	PO5	PO6	PO7	PO8	PO9	PO10	PO11	PO12	PSO1	PSO2
C304.1	2	2	2	2	-	-	-	-	-	-	1	2	3	3
C304.2	2	2	2	2	-	-	-	-	-	-	1	1	3	3
C304.3	2	2	2	2	-	-	-	-	-	-	1	2	3	3
C304.4	2	2	2	2	-	-	-	-	-	-	1	3	3	3
C304.5	2	2	2	2	-	-	-	-	-	-	1	2	3	3
C304.6	2	2	2	2	-	-	-	-	-	-	1	2	3	3

II. Identification of content beyond syllabus.

Table.2 Identification of content beyond syllabus

Details of Content Beyond Syllabus(CBS) added	POs strengthened/ vacant filled	CO/Unit
Scan based test techniques		5
Application Specific Integrated Circuits		5

III. Mapping of Course Outcomes with POs & PSOs. (After CBS)

Table.3 Mapping of COs, C, PSOs with POs- after CBS.

Course	PO1	PO2	PO3	PO4	PO5	PO6	PO7	PO8	PO9	PO10	PO11	PO12	PSO1	PSO2
C304.1	2	2	2	2	-	-	-	-	-	-	1	2	3	3
C304.2	2	2	2	2	-	-	-	-	-	-	1	1	3	3
C304.3	2	2	2	2	-	-	-	-	-	-	1	2	3	3
C304.4	2	2	2	2	-	-	-	-	-	-	1	3	3	3
C304.5	2	2	2	2	2	-	-	-	-	-	1	2	3	3
C304.6	2	2	2	2	-	-	-	-	-	-	1	2	3	3
C304	2	2	2	2	2	-	-	-	-	-	1	2	3	3

M. Nandhini
Signature of the Faculty

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N. V. S. S. S.
HoD/ECE

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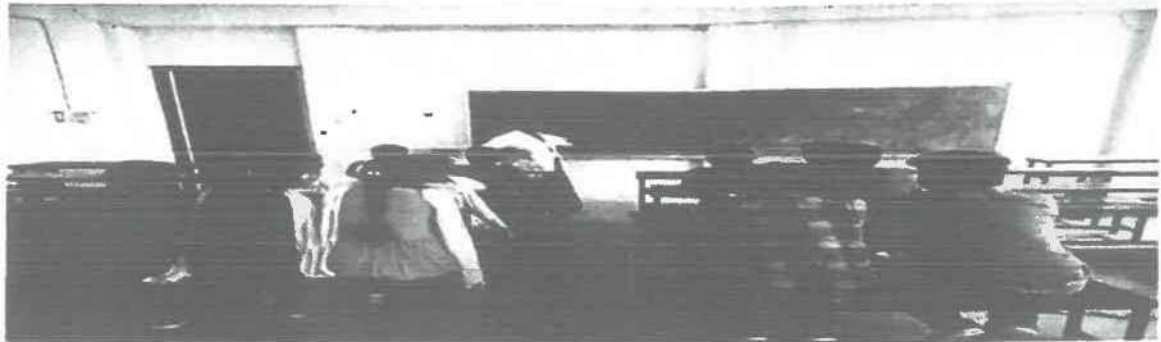
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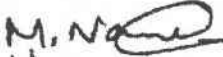
DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

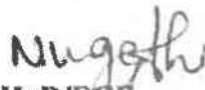
Proof of Curricular Gap & Content Beyond Syllabus(CBS)


Name of the Faculty :Ms.M.Nandhini
Degree & Program:B.E. /ECE
Academic Year: 2018 -2019 /EVEN

Course Code & Name:EC6601- VLSI DESIGN
Semester & Section: VI / B




Signature of the Faculty


HoD/ECE


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**DEPARTMENT OF ELECTRONICS AND COMMUNICATION
ENGINEERING**

Assignment Question Paper

Assignment – 01		Date of Issue:	04.01.2019	Marks	10
Course code	EC6601	Course Title	VLSI DESIGN		
Year	III	Semester/Section	VI/ B	Date of Submission:	11.01.2019

Q.No	Questions	CO
1	Explain the characteristics of Pass Transistor and Transmission gate	C304.2
2	Explain the static and dynamic power dissipation	C304.2

M. Nandhini

Name and Signature of the Faculty Incharge

(M. Nandhini)

N. Jagathi
HOD/ECE

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DEPARTMENT OF ELECTRONICS AND COMMUNICATION
ENGINEERING

Assignment Answer Sheet

Name of the Student :

AU Register Number:

Assignment – 01		Date of Issue:	04.01.2019	Marks	10
Course code	EC6601	Course Title	VLSI Design		
Year	III	Semester/Section	VI/ B	Date of Submission:	11.01.2019

Q.No	Questions	CO
1	Explain the characteristics of Pass Transistor and Transmission gate	C304.2
2	Explain the static and dynamic power dissipation	C304.2

Mark Allocation

Rubrics	Marks Allocated	Marks obtained
Content Quality	6	5
Presentation Quality	2	1
Timely submission	2	2
Total marks	10	8

M. Nandini
Name and Signature of the Faculty Incharge
(M. Nandini)



N. V. Jothi
HoD/ECE

Register Number:



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Internal Assessment Exam - I

Course code	EC6601	Course Title	VLSI DESIGN	Date/Session	24.01.2019	Marks	50
Regulation	2022	Duration	90 minutes	Academic Year	2018-19		
Year	III	Semester	VI	Department	ECE		

COURSE OUTCOMES

CO1:	In depth knowledge of MOS technology
CO2:	Explain the Combinational Logic Circuits and Design Principles
CO3:	Explain Sequential Logic Circuits and Clocking Strategies
CO4:	Explain the Memory architecture and building blocks
CO5:	Apply the ASIC Design Process and Testing
CO6:	Design using Programmable Devices (ROM, PLA, FPGA),

Q.No.	Question	CO	BTS
PART A			
(Answer all the Questions 10 x 2 = 20 Marks)			
1	Define Elmore constant	CO2	K1
2	Give the different symbols for transmission gate.	CO2	K1
3	What are the methods available to reduce dynamic power dissipation?	CO2	K3
4	Draw 2 input XNOR gate using nmos pass transistor	CO2	K1
5	What is meant by domino and pseudo nmos logic	CO2	K1
6	Implement a 2:1 multiplexer using pass transistor	CO2	K1
7	Draw 2 input XOR gate using nmos pass transistor	CO2	K3
8	What is transmission gate?	CO2	K1
9	List the sources of static and dynamic power dissipation	CO2	K3
10	What is dynamic power dissipation?	CO2	K1
PART B			
(Answer all the Questions 2 x 10 = 20 Marks)			
11a	Discuss in detail about RC delay model and Elmore delay model	CO2	K2
OR			
11b	Explain in detail with neat diagram about SFPL & CVSL	CO2	K3
12a	Write neat diagram for an expression $Y = (AB + (C+D)(DE))'$	CO2	K1
OR			
12b	Write neat diagram for an expression $Y = (A+B) + (C+D)(D+E)'$	CO2	K2
PART C			
(Answer all the Questions 1 x 10 = 10 Marks)			
13a	Realize a 2 input NOR gate using static CMOS logic, Domino logic and pseudo nmos logic (or)	CO2	K3
OR			
13b	Design a half adder using static CMOS logic Design a 4:1 MUX using 2:1 MUX. Realize it using transmission gate.	CO2	K4

M. Narasimhan

Course Faculty

(Name / Sign / Date)

M. Mandirani
24/1/2019

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Principal

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N. Vajayanthi

(Name / Sign / Date)

N. Vajayanthi
24/1/2019

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Internal Assessment Test Answer Book

Name	S. Anushya		Year/ Semester/Section	IV / VI / B
Batch No.	81121610600	Date/Session	24.01.19	Department
Course code	EE 6601	Course Title	VLSI Design	
Internal Assessment Test	IAT 1 <input type="checkbox"/>	IAT 2 <input checked="" type="checkbox"/>	IAT 3 <input type="checkbox"/>	Model <input type="checkbox"/>
Name and Signature of the Invigilator with date			M. Bhuvaneshwari	

Instruction to the Student: Put tick mark to the question attended in the column against question.

Part A			Part B / Part C				Total Marks
Q. No.	✓	Marks	Q. NO.	✓	a	b	
					Marks	Marks	
1		1	11		09		
2		1	12		7		
3		2	13			8	
4		2	14				
5		2	15				
6		1	16				
7		2	Total			24	
8		—	38/50				M. Nandhini (M. Nandhini) Name and Signature of the Examiner with date (26/1/2019)
9		2					
10		1					
Total		14	Grand Total				

To be filled by the examiner							
Course Outcomes	1	2	3	4	5	6	Total
Marks allotted		50					
Marks Obtained		38					
IQAC Audit - Remarks							
Try to get high marks							Nandhini Name and Signature of the IQAC member

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IG VALLEY, MANIDANDAM, TIRUCHIRAPPALLI - 620012

DEPARTMENT OF ECE

ACADEMIC YEAR 2018 - 2019 (EVEN SEMESTER)

STUDENTS MARK STATEMENT- CO BASED

CYCLE TEST-II

SUBJECT CODE & TITLE: EC6601 & VLSI DESIGN

YEAR/SEM: III/VI

MONTH & YEAR: 01/2019

S.NO	REG NO	STUDENT NAME	CO2	Retest CO2	TOTAL	TOTAL (100)
					60	
1	Abarna T	811216106001	40		40	67
2	Amsavalli S	811216106002	52		52	87
3	Anushya S	811216106003	42		42	70
4	Arockia Nivetha S	811216106004	38		38	63
5	Ashefa N	811216106005	35		35	58
6	Dhanalakshmi T	811216106006	AB	35	35	58
7	Femina Begum A	811216106008	38		38	63
8	Gayathri J	811216106009	35		35	58
9	Joysefshiba J	811216106010	32		32	53
10	Keerthana P	811216106011	48		48	80
11	Keerthana S	811216106012	40		40	67
12	Keerthika D	811216106013	38		38	64
13	Lathasri S	811216106014	48		48	80
14	Menaka R	811216106015	52		52	87
15	Mithra P	811216106016	32		32	53
16	Mohan Raj S	811216106017	35		35	58
17	Nilavar Nisha F	811216106018	32		32	53
18	Pavithra P	811216106019	8	30	30	50
19	Pavithra V	811216106020	40		40	67
20	Prabhu A	811216106021	45		45	75
21	Preetha M	811216106022	45		45	75
22	Prema S	811216106024	45		45	75
23	Raahul BN	811216106025	40		40	67
24	Ramya S	811216106026	45		45	75
25	Ruban Raj S	811216106027	48		48	80
26	Saranya M	811216106028	35		35	58
27	Saravanan S	811216106030	40		40	67
28	Shanakya P	811216106031	48		48	80
29	Sorna J	811216106032	35		35	58
30	Sudharsan K	811216106033	30		30	50
31	Suvathi R	811216106034	42		42	70
32	Swathi S	811216106035	48		48	80
33	Udaya Rani K	811216106036	30		30	50
34	Vettai P	811216106037	35		35	58

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MARKS RANGE:

<20	20-30	31-40	41-50	51-60	61-70	71-80	81-90	91-100
			03	10	10	9	2	

Total No.of Candidates Present	33
Total No.of Candidates Absent	01
Total No.of Students Pass	32
Total No. of Students Fail	01
Percentage of Pass	98

M. Nandhin
STAFF INCHARGE

N. Uggchi
HoD/BCE

[Signature]
PRINCIPAL

[Signature]
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INDRA GANESAN COLLEGE OF ENGINEERING

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(Approved by AICTE, New Delhi, Affiliated to Anna University, Chennai-25)

DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

ROOT CAUSE ANALYSIS

Name of the Faculty : Ms. M. Nandhini
Degree & Program : B.E & ECE
IA Test : II
Target : 100 %

Course Code & Name : EC 6601 & VLSI Design
Semester & Section : VI & B
University Exam / Month & Year : APR - MAY 2019
Achieved : 98 %

S.NO	BATCH NO	NAME OF THE STUDENT	CAUSES FOR FAILURE	SIGNATURE OF THE STUDENT WITH DATE	CORRECTIVE ACTION TAKEN	PREVENTIVE ACTION TAKEN	FOLLOWUP STATUS	REMARKS OF THE HOD
1.	811216106006	DHANALAKSHMI T	WENT TO DEATH	T. Dhanya 5/12/19	RETEST	ADVISED	PROGRESS MONITORED	
2.	811216106019	PAVITHRA P	FEVER.	Pavithra 5/12/19	RETEST	ADVISED	PROGRESS MONITORED	

M. Nandhini

Signature of the Faculty Member

Dr. G. Bakkrishnan, M.E., Ph.D.,
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N. Pavithra

Signature of the HoD/ECE



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IOAC Academic Audit Form

ACADEMIC YEAR: 2018-2019 ODD / EVEN SEMESTER

Name of Department : ECE Year / Sem / Sec : 2 / III / A No. of Students Registered : 120

Details of Examination : IA Test -1 / IA Test -2 / IA Test -3 / Model Test

S.No.	Course Code	List of Reg.No Verified	Course Log Book Verified (Y/N)	Course File Verified (Y/N)	No of students Attended	No of Absentees	No of Failures	Pass %	Remarks
1.	MG6851	811216106001	Y	Y	50	01	8	84	Try to get 100% Percent
2	CS6303	811216106005	Y	Y	51	-	4	92	Presentations clear.
3	CS6551	811216106013	Y	Y	50	1	5	90	Content ok
4	EC6601	811216106025	Y	Y	50	1	1	98	Presentations Fine
5	EC6602	811216106026	Y	Y	48	3	4	92	Try to get 100%.
6.	EC6001	811216106030	Y	Y	51	-	3	94	Pass percent 100%.

Verified by

External Member Name and Signature:

N. Vajayanthi

Internal Member Name and Signature:

M. Nandhini

Overall Remarks:

N. Vajayanthi
HoD/ ECE

N. Vajayanthi
IOAC Co-ordinator

Principal

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DEPARTMENT OF ELECTRONICS AND COMMUNICATION

ENGINEERING

Identification of Curricular Gap & Content Beyond Syllabus(CBS) Material

Scan-Based Techniques

The controllability and observability can be enhanced by providing more accessible logic nodes with use of additional primary input lines and multiplexors. However, the use of additional I/O pins can be costly not only for chip fabrication but also for packaging. A popular alternative is to use scan registers with both shift and parallel load capabilities. The scan design technique is a structured approach to design sequential circuits for testability. The storage cells in registers are used as observation points, control points, or both. By using the scan design techniques, the testing of a sequential circuit is reduced to the problem of testing a combinational circuit.

In general, a sequential circuit consists of a combinational circuit and some storage elements. In the scan-based design, the storage elements are connected to form a long serial shift register, the so-called scan path, by using multiplexors and a mode (test/normal) control signal, as shown in Fig. 1 .

In the test mode, the scan-in signal is clocked into the scan path, and the output of the last stage latch is scanned out. In the normal mode, the scan-in path is disabled and the circuit functions as a sequential circuit. The testing sequence is as follows:

- Step 1: Set the mode to test and, let latches accept data from scan-in input.
- Step 2: Verify the scan path by shifting in and out the test data.
- Step 3: Scan in (shift in) the desired state vector into the shift register.
- Step 4: Apply the test pattern to the primary input pins.
- Step 5: Set the mode to normal and observe the primary outputs of the circuit after sufficient time for propagation.,
- Step 6: Assert the circuit clock, for one machine cycle to capture the outputs of the combinational logic into the registers.
- Step 7: Return to test mode; scan out the contents of the registers, and at the same time scan in the next pattern.
- Step 8: Repeat steps 3-7 until all test patterns are applied.

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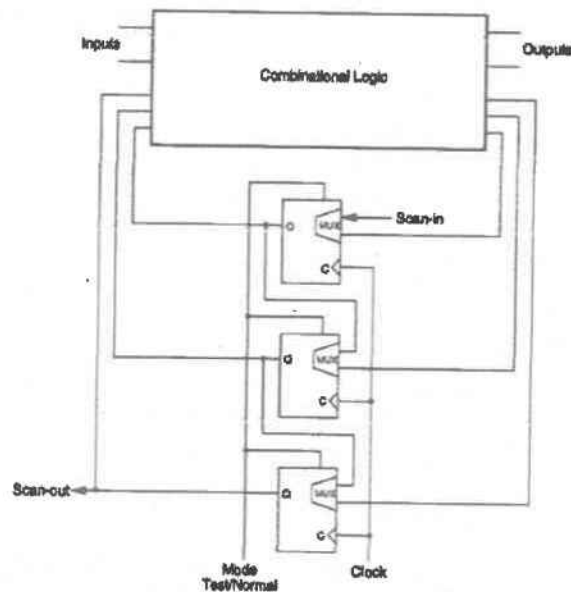
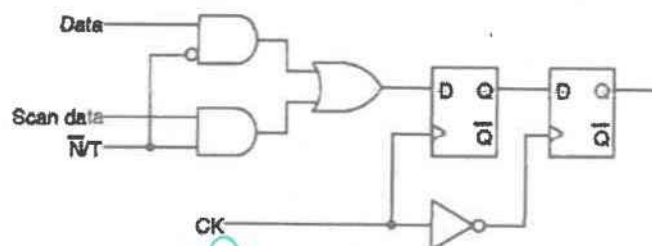


Figure 1: The general structure of scan-based design

The storage cells in scan design can be implemented using edge-triggered D flipflops, master-slave flip-flops, or level-sensitive latches controlled by complementary clock signals to ensure race-free operation. Figure 2 shows a scan-based design of an edge-triggered D flip-flop. In large high-speed circuits, optimizing a single clock signal for skews, etc., both for normal operation and for shift operation, is difficult. To overcome this difficulty, two separate clocks, one for normal operation and one for shift operation, are used. Since the shift operation does not have to be performed at the target speed, its clock is much less constrained.

An important approach among scan-based designs is the level sensitive scan design (LSSD), which incorporates both the level sensitivity and the scan path approach using shift registers. The level sensitivity is to ensure that the sequential circuit response is independent of the transient characteristics of the circuit, such as the component and wire delays. Thus, LSSD removes hazards and races. Its ATPG is also simplified since tests have to be generated only for the combinational part of the circuit.



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Figure 2 : Scan-based design of an edge-triggered D flip-flop

The boundary scan test method is also used for testing printed circuit boards (PCBs) and multichip modules (MCMs) carrying multiple chips. Shift registers are placed in each chip close to I/O pins in order to form a chain around the board for testing. With successful implementation of the boundary scan method, a simpler tester can be used for PCB testing.

On the negative side, scan design uses more complex latches, flip-flops, I/O pins, and interconnect wires and, thus, requires more chip area. The testing time per test pattern is also increased due to shift time in long registers

Application-specific integrated circuit

An application-specific integrated circuit (ASIC /'eɪsɪk/) is an integrated circuit (IC) chip customized for a particular use, rather than intended for general-purpose use, such as a chip designed to run in a digital voice recorder or a high-efficiency videocodec. Application-specific standard product chips are intermediate between ASICs and industry standard integrated circuits like the 7400 series or the 4000 series.

[1] ASIC chips are typically fabricated using metal-oxide-semiconductor (MOS) technology, as MOS integrated circuit chips.

[2]As feature sizes have shrunk and chip design tools improved over the years, the maximum complexity (and hence functionality) possible in an ASIC has grown from 5,000 logic gates to over 100 million. Modern ASICs often include entire microprocessors, memory blocks including ROM, RAM, EEPROM, flash memory and other large building blocks.

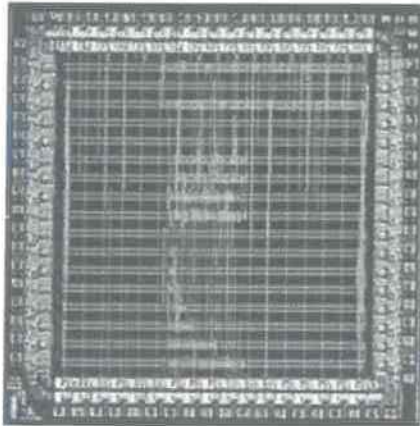
Such an ASIC is often termed a SoC (system-on-chip). Designers of digital ASICs often use a hardware description language (HDL), such as Verilog or VHDL, to describe the functionality of ASICs.

[1]Field-programmable gate arrays (FPGA) are the modern-day technology improvement on breadboards, meaning that they are not made to be application-specific as opposed to ASICs. Programmable logic blocks and programmable interconnects allow the same FPGA to be used in many different applications. For smaller designs or lower production volumes, FPGAs may be more cost-effective than an ASIC design, even in production. The non-recurring engineering (NRE) cost of an ASIC can run into the millions of dollars. Therefore, device manufacturers typically prefer FPGAs for prototyping and devices with low production volume and ASICs for very large production volumes where NRE costs can be amortized across many devices.▣

Gate-array and semi-custom design

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Microscope photograph of a gate-array ASIC showing the predefined logic cells and custom interconnections. This particular design uses less than 20% of available logic gates.

Gate array design is a manufacturing method in which diffused layers, each consisting of transistors and other active devices, are predefined and electronics wafers containing such devices are "held in stock" or unconnected prior to the metallization stage of the fabrication process. The physical design process defines the interconnections of these layers for the final device. For most ASIC manufacturers, this consists of between two and nine metal layers with each layer running perpendicular to the one below it. Non-recurring engineering costs are much lower than full custom designs, as photolithographic masks are required only for the metal layers. Production cycles are much shorter, as metallization is a comparatively quick process; thereby accelerating time to market.

Gate-array ASICs are always a compromise between rapid design and performance as mapping a given design onto what a manufacturer held as a stock wafer never gives 100% circuit utilization. Often difficulties in routing the interconnect require migration onto a larger array device with a consequent increase in the piece part price. These difficulties are often a result of the layout EDA software used to develop the interconnect.

Pure, logic-only gate-array design is rarely implemented by circuit designers today, having been almost entirely replaced by field-programmable devices. The most prominent of such devices are field-programmable gate arrays (FPGAs) which can be programmed by the user and thus offer minimal tooling charges, non-recurring engineering, only marginally increased piece part cost, and comparable performance.

Today, gate arrays are evolving into structured ASICs that consist of a large IP core like a CPU, digital signal processor units, peripherals, standard interfaces, integrated memories, SRAM, and a block of reconfigurable, uncommitted logic. This shift is largely because ASIC devices are capable of integrating large blocks of system functionality, and systems on a chip (SoCs) require glue logic, communications subsystems (such as networks on chip), peripherals, and other components rather than only functional units and basic interconnection.


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In their frequent usages in the field, the terms "gate array" and "semi-custom" are synonymous when referring to ASICs. Process engineers more commonly use the term "semi-custom", while "gate-array" is more commonly used by logic (or gate-level) designers.


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